5-104319-3 ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 5-104319-3

PCB Mount Header, Right Angle, Wire-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder,

AMPMODU Headers

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Connector System: Wire-to-Board

Number of Positions: 30

Number of Rows: 2

Centerline (Pitch): 2.54 mm [.1 in]
PCB Mount Orientation: Right Angle

Features

Product Type Features

Connector System	Wire-to-Board
Header Type	Fully Shrouded
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header

Configuration Features

Connector Contact Load Condition	Fully Loaded
Number of Positions	30
Number of Rows	2
PCB Mount Orientation	Right Angle

Electrical Characteristics

Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Operating Voltage	30 VAC

Body Features

Connector Profile	Standard
Primary Product Color	Black

Contact Features

Mating Square Post Dimension	.64 mm[.025 in]	
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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
Contact Underplating Material	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.43 mm[.135 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Boardlock
Mating Retention Type	Latching
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	With
PCB Mount Retention	With
Housing Features	
Housing Material	Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
PCB Thickness (Recommended)	1.4 mm[.055 in]
Row-to-Row Spacing	2.54 mm[.1 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	



Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Compatible With Agency/Standards Products	CSA
Compatible With Approved Standards Products	CSA LE7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	13
Packaging Method	Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts







30 MODIV HSG COMP DR .100 POL

TE Part # 86177-6 30 MODIV HSG COMP DR .100CL

TE Part # 2-87456-5 30 MODIV HSG COMP DR .100CL

Also in the Series | AMPMODU Headers









Connector Caps & Covers(1)

Connector Contacts(64)

Connector Hardware(2)

PCB Headers & Receptacles(3197)



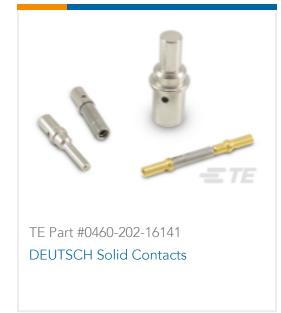
& Housings(5)

Customers Also Bought















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Documents

Datasheets & Catalog Pages

AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English